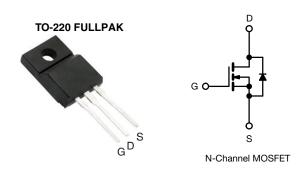
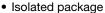


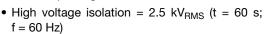
Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	60				
R _{DS(on)} (Ω)	V _{GS} = 5.0 V 0.20				
Q _g (Max.) (nC)	8.4				
Q _{gs} (nC)	3.5				
Q _{gd} (nC)	6.0				
Configuration	Single				

FEATURES







- Sink to lead creepage distance = 4.8 mm
- · Logic-level gate drive
- R_{DS(on)} specified at V_{GS} = 4 V and 5 V
- · Fast switching
- · Ease of paralleling
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION			
Package	TO-220 FULLPAK		
Lead (Pb)-free	IRLIZ14GPbF		

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	60	V
Gate-source voltage			V_{GS}	± 10	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Continuous drain current	V at 5.0 V	T _C = 25 °C T _C = 100 °C	I_	8.0	
Continuous diain current	V _{GS} at 5.0 V	T _C = 100 °C	I _D	5.7	Α
Pulsed drain current ^a			I _{DM}	32	
Linear derating factor				0.18	W/°C
Single pulse avalanche energy b			E _{AS}	39.5	mJ
Maximum power dissipation $T_C = 25 ^{\circ}C$		P_{D}	27	W	
Peak diode recovery dV/dt ^c			dV/dt	4.5	V/ns
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) d	For 10 s			300	7
Mounting torque M3 screw			0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 0.79 mH, R_G = 25 Ω , I_{AS} = 10 A (see fig. 12)
- c. $I_{SD} \le 10$ A, $dI/dt \le 90$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 175$ °C
- d. 1.6 mm from case

S21-0978-Rev. D, 11-Oct-2021



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	5.5	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-ssource breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.070	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.0	-	2.0	V
Gate-source leakage	I _{GSS}	,	V _{GS} = ± 10 V	-	-	± 100	nA
7		V _{DS} =	= 60 V, V _{GS} = 0 V	-	-	25	μА
Zero gate voltage drain current	I _{DSS}	V _{DS} = 48 V,	V _{GS} = 0 V, T _J = 150 °C	-	-	250	
Duning and an add an airthuigh	0	V _{GS} = 5.0 V	$I_D = 4.8 A^b$	-	-	0.20	0
Drain-source on-state resistance	$R_{DS(on)}$	V _{GS} = 4.0 V	I _D = 4.0 A ^b	-	-	0.28	Ω
Forward transconductance	9 _{fs}	V _{DS} =	25 V, I _D = 4.8 A ^b	3.6	-	-	S
Dynamic							
Input capacitance	C _{iss}		V _{GS} = 0 V,	-	400	-	_
Output capacitance	C _{oss}		$V_{DS} = 25 \text{ V},$	-	170	-	
Reverse transfer capacitance	C _{rss}	f = 1.0 MHz, see fig. 5		-	42	-	pF
Drain to sink capacitance	С	f = 1.0 MHz		-	12	-	
Total gate charge	Qg			-	-	8.4	
Gate-source charge	Q _{gs}	V _{GS} = 5.0 V	$V_{GS} = 5.0 \text{ V}$ $I_D = 10 \text{ A}, V_{DS} = 48 \text{ V},$ see fig. 6 and 13 ^b		-	3.5	nC
Gate-drain charge	Q _{gd}		See fig. 6 and 16	-	-	6.0	1
Turn-on delay time	t _{d(on)}	$V_{DD} = 30 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 12 \Omega, R_{D} = 2.8 \Omega,$ see fig. 10^{b}		-	9.3	-	- ns
Rise time	t _r			-	110	-	
Turn-off delay time	t _{d(off)}			-	17	-	
Fall time	t _f			-	26	-	
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal source inductance	L _S			-	7.5	-	nH
Drain-Source Body Diode Characteristic	cs			·			I
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8.0	А
Pulsed diode forward current ^a	I _{SM}			-	-	32	
Body diode voltage	V_{SD}	T _J = 25 °C	, I _S = 8.0 A, V _{GS} = 0 V ^b	-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T 25 °C 1	- 10 A dl/dt - 100 A/v-ah	-	65	130	ns
Body diode reverse recovery charge	Q _{rr}	$-$ T _J = 25 °C, I _F = 10 A, dI/dt = 100 A/ μ s ^b		-	0.33	0.65	μC
Forward turn-on time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

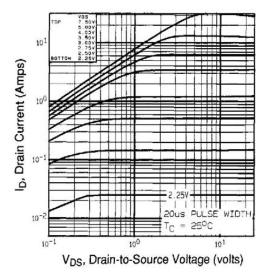


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

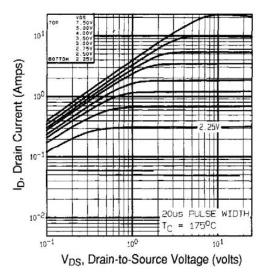


Fig. 2 - Typical Output Characteristics, T_C= 175 °C

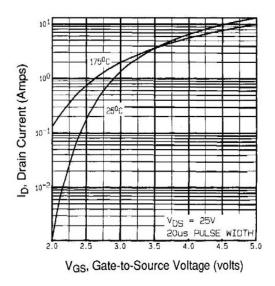


Fig. 3 - Typical Transfer Characteristics

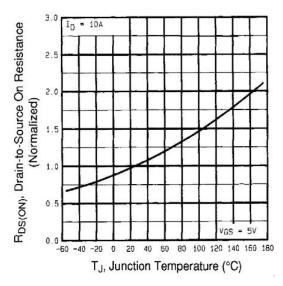


Fig. 4 - Normalized On-Resistance vs. Temperature



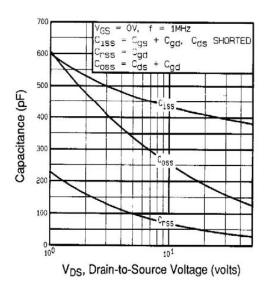


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

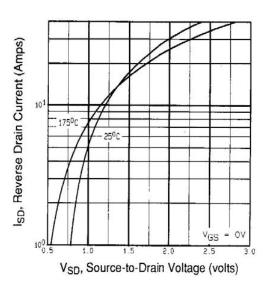


Fig. 7 - Typical Source-Drain Diode Forward Voltage

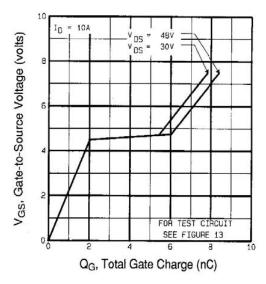


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

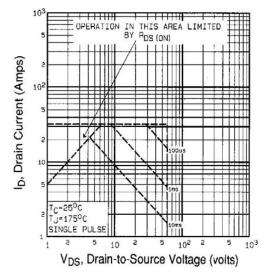


Fig. 8 - Maximum Safe Operating Area



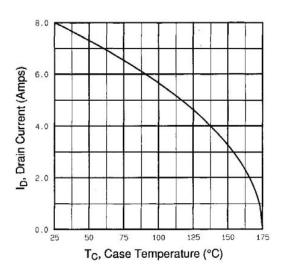


Fig. 9 - Maximum Drain Current vs. Case Temperature

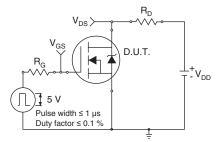


Fig. 10a - Switching Time Test Circuit

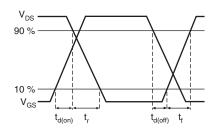


Fig. 10b - Switching Time Waveforms

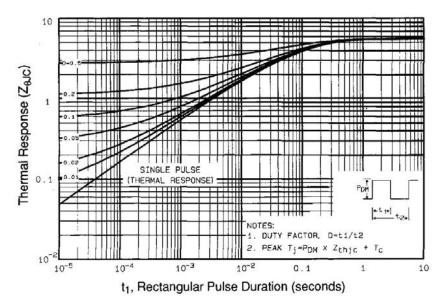


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



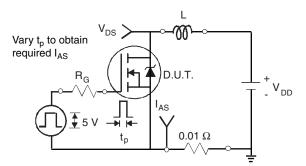


Fig. 12a - Unclamped Inductive Test Circuit

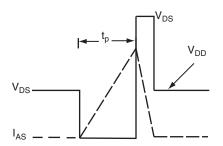


Fig. 12b - Unclamped Inductive Waveforms

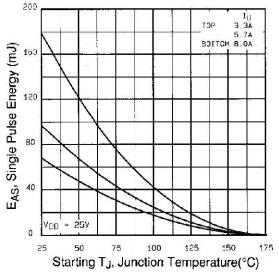


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

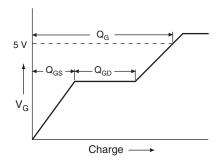


Fig. 13a - Basic Gate Charge Waveform

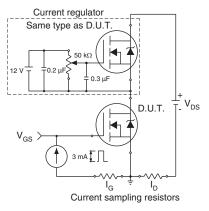
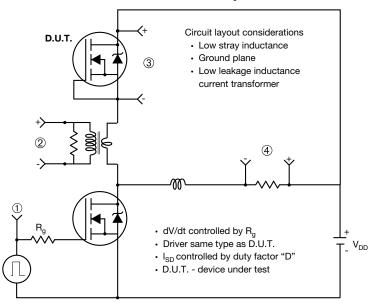


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



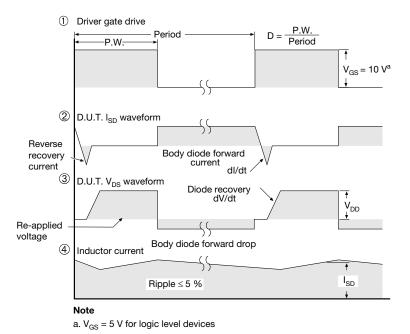


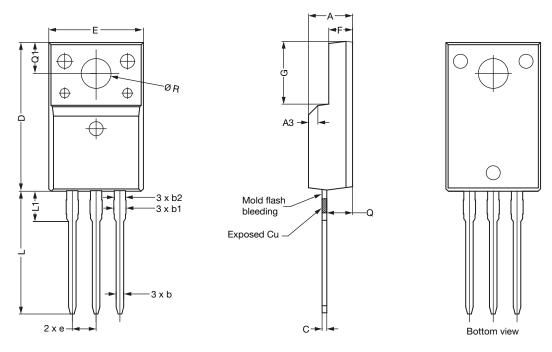
Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg291315.

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TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9



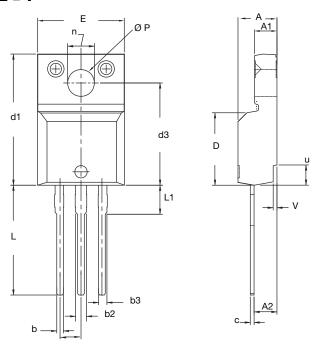
	MILLIMETERS			
DIM.	MIN.	NOM.	MAX.	
A	4.60	4.70	4.80	
b	0.70	0.80	0.91	
b1	1.20	1.30	1.47	
b2	1.10	1.20	1.30	
С	0.45	0.50	0.63	
D	15.80	15.87	15.97	
е	2.54 BSC			
E	10.00	10.10	10.30	
F	2.44	2.54	2.64	
G	6.50	6.70	6.90	
L	12.90	13.10	13.30	
L1	3.13	3.23	3.33	
Q	2.65	2.75	2.85	
Q1	3.20	3.30	3.40	
ØR	3.08	3.18	3.28	

Notes

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



OPTION 2: FACILITY CODE = Y



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
Е	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	
ECN: E10 0190 Pov D (00 Apr 2010	•			

ECN: E19-0180-Rev. D, 08-Apr-2019

DWG: 5972

Notes

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- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
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